



Material Content Data Sheet



Sales Product Name		SS05N70		Issued		19. July 2018			
MA#		MA001091794							
Package		PG-TO251-3-342		Weight*		317.92 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.898	0.60	0.60	5969	5969	
leadframe	non noble metal	iron	7439-89-6	0.147	0.05		463		
	inorganic material	phosphorus	7723-14-0	0.044	0.01		139		
	non noble metal	copper	7440-50-8	147.096	46.26	46.32	462687	463289	
wire	non noble metal	aluminium	7429-90-5	0.546	0.17	0.17	1719	1719	
encapsulation	organic material	carbon black	1333-86-4	1.417	0.45		4458		
	plastics	epoxy resin	-	24.802	7.80		78014		
	inorganic material	silicondioxide	60676-86-0	115.507	36.33	44.58	363323	445795	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11764	11764	
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11		
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4468	4479	
solder	noble metal	silver	7440-22-4	0.052	0.02		165		
	non noble metal	tin	7440-31-5	0.042	0.01		132		
	non noble metal	lead	7439-92-1	1.999	0.63	0.66	6288	6585	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		60		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	copper	7440-50-8	19.177	6.03	6.04	60322	60400	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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